

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	711234	(semiconductor si silicon gaas) with (substrate carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:28
L2	187813	(bond bonded bonding) with (terminal electrode pad paddle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:29
L3	794	(via hole thru through opening) with (dielectroc lox ((ladder adj4 oxide) adj3 (o oxide)) (ladder with (sio (silicon adj (dioxide oxide))))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:31
L4	121898	(via hole thru through opening) with (dielectric lox ((ladder adj4 oxide) adj3 (o oxide)) (ladder with (sio (silicon adj (dioxide oxide))))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:31
L5	5566	1 and 2 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:31
L6	503	1 same 2 same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:32
L7	3404	5 and (copper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:32
L8	70	6 same (copper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:32

L9	2565	(interconnect interconnecting interconnected interconnection) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:33
L10	46	(interconnect interconnecting interconnected interconnection) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:57
L11	1142	9 and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:57
L12	1114	11 not 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 05:57